



Laserbonder M17LSB

F & K DELVOTEC – Partner for Tomorrow’s Interconnection Technology.

Developed in close co-operation with Fraunhofer Institute for Laser Technology in Aachen, the combination of ultrasonic bonding and laser welding offers the best of both worlds.

It is ideal for package interconnects in power modules and for battery pack assembly. Aluminium, copper or nickel ribbons are welded by laser energy at low bond forces. The process offers a larger range of choice in very diverse joining materials, compared to ultrasonic bonding. As a further advantage, it is very easy to automate.

Advantages

- **The best of both worlds:
Combination of laser welding and wire bonding**
- Higher current carrying capability with larger connector cross sections compared to ultrasonic wire bonding
- Lowers manufacturing costs through reduced demands on the surface quality of the parts to be connected
- Allows XYZ positional tolerance compared to laser welding through use of touch down sensor and pattern recognition
- No damage to parts because of lower clamping forces in the work holder
- Combines three processes in a single machine without modification:
 - Laser bonding of ribbon
 - Laser-tab-bonding of connections
 - LIMBO

NOT JUST MACHINES.
BUT BONDING SOLUTIONS.

MADE FOR YOU - YOUR ADVANTAGES AT A GLANCE

M17 LSB

500 W

- CW infrared
- Power modulation
- PCB connections
- Al/Cu ribbon thickness 100 µm

M17 LSB

1,000 W

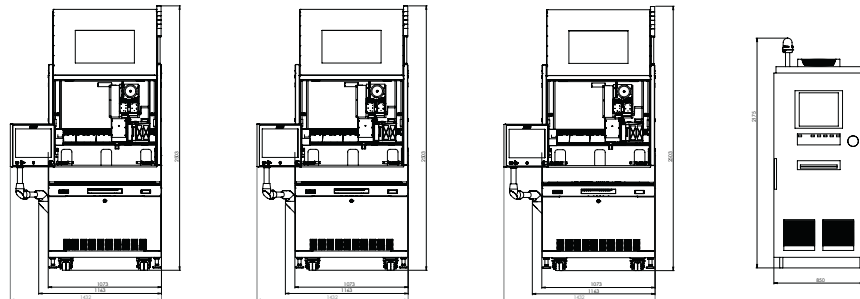
- CW infrared
- Power modulation
- TAB Bonding up to 800 µm thickness
- Suitable for battery pack connections
- Al/Cu/Ni ribbon thickness up to 500 µm

M17 LSB

1,500 W

- CW infrared
- Power modulation
- TAB Bonding up to 800 µm thickness
- Suitable for battery pack connections
- Al/Cu/Ni ribbon thickness up to 500 µm

LASERBONDER MACHINE MODEL



| M17LSB | 500 W | 1,000 W | 1,500 W | Laser Unit |
|---------------------------------|--|------------------|------------------|--------------|
| X-axis | 595 mm (23.5") | 595 mm (23.5") | 595 mm (23.5") | |
| Y-axis | 340 mm (13.4") | 340 mm (13.4") | 340 mm (13.4") | |
| Z-axis | 100 mm (4") | 100 mm (4") | 100 mm (4") | |
| Width | 1,073 mm | 1,073 mm | 1,073 mm | 850 mm |
| Height with/without signal lamp | 2,501 / 1,975 mm | 2,501 / 1,975 mm | 2,501 / 1,975 mm | 2,175 mm / - |
| Depth | 1,565 mm | 1,565 mm | 1,565 mm | 1,200 mm |
| Weight | 1,100 kg | 1,100 kg | 1,100 kg | 510 kg |
| Working height | SMEMA compliant 850-1,050 mm | | | |
| Power supply | 3P / 200 V / 208 V / 230 V / 400 V / PE; 50 Hz / 60 Hz | | | |
| Compressed air | 4-8 bar | | | |
| Vacuum connection | < -0.8 bar | | | |
| Optional | Supply for water-water cooler, purging gas for N2 | | | |

LASER UNIT

- **Ribbon materials**
Al, Au, Ag, Ptlr, Pt, Cu, Ni
- **Ribbon dimensions**
 - Max. cross sections up to 5,000 μm x 500 μm
 - Min. cross sections down to 500 μm x 100 μm
 - Customer specific dimensions on request
- **Joining materials**
 - Al, die-cast Al, Cu, Ni, brass, bronze, steel
 - Other metals on request
- **Ribbon spool**
 - Spool diameter 3", 3,5", 4"
 - Larger diameters optional
 - Automatic ribbon feed
 - Detection of ribbon end by CCD sensor
- **Cutting process**
Active, programmable cut depth, front cut
- **Bond tool**
Special tools of length 50 mm, 60 mm, 70 mm, 90 mm, 100 mm & 110 mm
- **Touchdown sensor**
 - Inductive sensor with linear working range
 - Anti-crash hardware sensor
- **Laser power**
500 W, 1,000W, 1,500 W (each freely adjustable between 10 and 100 %)
- **Optics variants**
 - Optics for tools 50 to 70 mm
 - Optics for tools 90 to 110 mm for extreme cavity depth
- **Adaptation to tool lengths**
Tracking of laser focus position for different tool lengths and varying touchdown speeds
- **Focus spot diameter**
< 50 μm for tool length 60 mm and 100 mm, resp.
- **Beam quality M²**
 ≤ 1.5
- **Laser beam source**
CW fibre laser with fundamental mode radiation
- **Speed**
 - Speed up to 1 wire/sec (depending on application)
 - Welding time depending on ribbon width and the desired connection area
 - Simple scale-up of connection area possible

LASERBONDER MACHINE MODEL

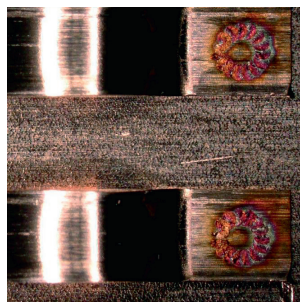
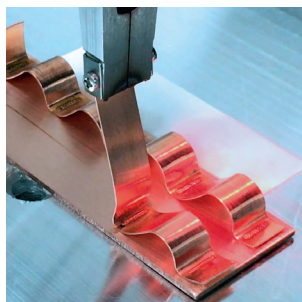
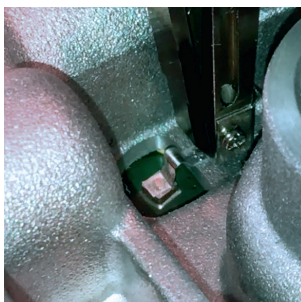
M17 LSB



MACHINE SPECIFICATION

MACHINE BASE

| | |
|------------------------------|--|
| X-Y-axes | Linear encoder resolution better than 0.1 μm |
| P-axis | +/- 180° AC servomotor with absolute encoder, resolution 0.0035° |
| Z-axis | Up to 100 mm, AC servomotor with absolute encoder, resolution 0.5 μm |
| Positional accuracy | < +/-5 μm @ 3 sigma, incl. PRU/Wire/Tool/Application |
| Repeatability on the product | < +/-3 μm @ 3 sigma, incl. PRU/Wire/Tool/Application |
| Working height | According to SMEMA 850-1,050 mm |
| Monitor | 21" flat screen |
| Certification | SEMI S2, CE, Laser Unit Class 1 according to EN 60825-1:2014 |
| Connections | SMEMA, USB, RJ 45, Digital I/O |
| Operating system | Real-time, Unix®-based multi-tasking OS |
| Pattern recognition unit | Cognex® PatMax® System |
| Recognition time | Up to 2 ms per pattern recognition |
| Alignment correction | NEW Flexsearch, single point recognition incl. phase angle, two point recognition, phase angle correction +/- 5 % |
| Precision | Sub-pixel resolution down to 0.1 pixel |
| Camera | Moving CCD-camera, 640 x 480 pixel |
| Resolution | Standard approx. 30 μm per pixel, adjustable using different optics |
| Image size | Standard 19.2 x 14.4 mm, adjustable using different optics |
| Illumination | Ring light, red, blue, white |
| Manual work stations | From standard size for PCB 4" x 4", 6" x 6", 8" x 6", 10" x 6", 10" x 8" up to 650 mm x 350 mm (25" x 14"), vacuum and / or mechanical clamping |
| Automatic parts handling | Belt indexer for flat substrates, e. g. ceramic substrates, PCB or workpiece carriers, substrate length: flexible, according to requirements; substrate width up to 350 mm |
| Network connectivity | TCP/IP/FTP data exchange, SMEMA for in-line connections to other machines, SEMI communication standard SECS/GEM, MES host connectivity |



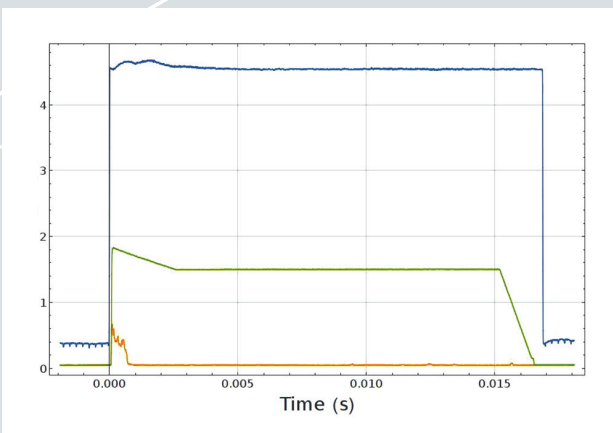
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QUALITY TOOLS

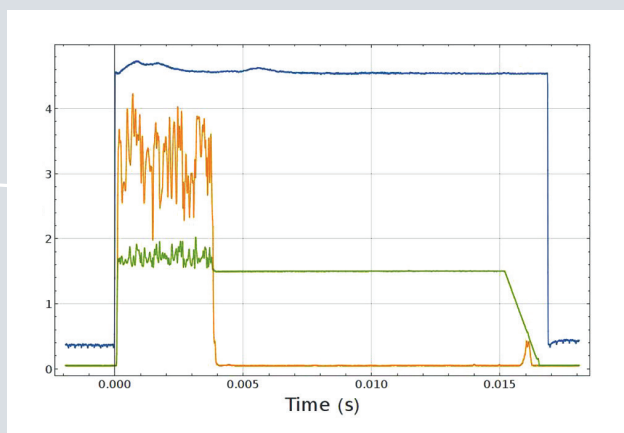
Laser quality monitoring

The laserbonder can be equipped with a process control system which permits real-time monitoring of standard welding processes. It supplies quality data on every single bond by detecting deviations from the programmed welding parameters as well as process fluctuations. The welding process is compared to characteristic references which are a composite of various signals, automatically supporting the user when deciding about OK or NOK classifications for the joint.

Part OK



Part Not OK



Further information about the system is available upon request.

Laser adjustment kit

- Camera system and PRU for easy adjustment and checking the bond tool
- Software based adjustment of laser beam relative to the bond tool and tuning of the focus position
- Graphical display of the target position of bond tool and cutter
- Minimal adjustment time when changing bond tool and cutter
- Detection of tool contamination and prevention of faults

Traceability

- Connection of standard F & K or customized MES
- Connection to existing host system
- Storing, retrieving and transferring process settings per wire
- Parts traceability by barcode or RFID
- SECS/GEM state monitoring

Barcode & DMC-Reader

- Fully automatic part recognition, recipe and process data assignment
- Available as flexible hand-held DMC-reader or fixed-position integrated unit

Expanding process limits by

- Combination of CW micro and oscillation welding
- Excellent beam quality and high dynamic range of beam motion for improved weld seam strength
- Optimal adaptation of connection area between ribbon and substrate
- Welding depth and seam width independently adjustable
- Flexible laser power modulation for varying requirements in amplitude and frequency
- Optimal quality monitoring

BOND ACADEMY: your advantages?

Our support for implementing your requirements and optimising your processes:

- Competent advice
- Determining the correct transducer frequency for the application
- Rapid prototyping
- Validation of product design
- Sample bond tests and pilot series manufacture
- Training your service technicians
- Ramp-up-support



POWERFUL SYNERGIES AS „MEMBER OF STRAMA GROUP“

Together with our parent company, Strama-MPS, we integrate our wirebonders into complete assembly lines with other joining, assembling and testing stations. Our customers profit from the combination of our bonding and automotive expertise, „One-stop-shopping“, and the interface free quality of the complete package.



GERMANY, Straubing
HUNGARY, Budapest
CHINA, Taicang
USA, Duncan
MEXICO, Puebla
INDIA, Nashik



GERMANY, Kassel



CROATIA,
Cerna
Gradište
GERMANY,
Osterhofen



GERMANY, Ottobrunn
USA, Foothill Ranch
CHINA, Taicang
SINGAPORE

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